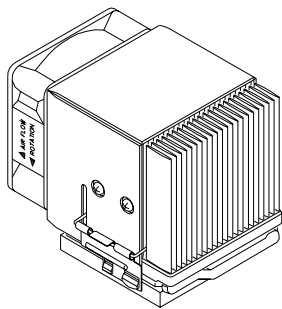


ALPHA

PEP66 Installation Guide

Nov,2002

X001ZF0E-D



PAD

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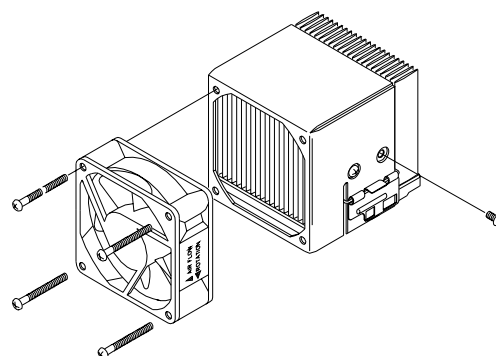
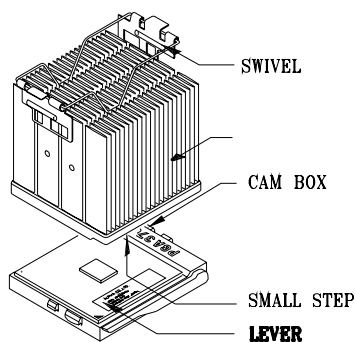
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Heat sink unit.

The small step goes over the lever arm. The large step goes over the socket cam box.

Be sure to insert the clip in the direction shown in the following figure. The swivel portion of the clip should attach to the cam box side of the Socket.

tighten.

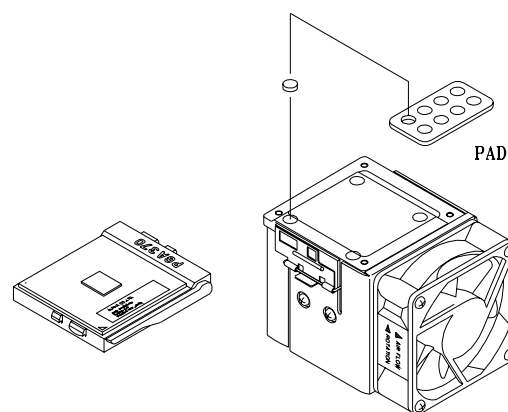


The base is coated with oil that prevents oxidation.

Remove this coating with a clean cloth. To ensure proper bonding of PADS (see below), the use of a mild solvent, such as isopropyl alcohol or acetone (nail polish remover), would be ideal.

STEP 4

- For the attachment to FC-PGA.
Apply PADS to the four points on the heat sink base shown in the right-hand side diagram. (PADS which remain are spares.)
- For the attachment to Athlon, Duron and PPGA chips, do not use PADS.



STEP 5

Apply thermal grease to heat sink and CPU thinly and evenly.

NOTE : Applying excessive thermal grease causes decrease in thermal performance.

To avoid possible board damage, do not use excessive force. Make sure the clip is installed correctly on socket tab.